TAS5720M Evaluation Board

User's Guide

Literature Number: SLOU437
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Introduction

To help the user investigate and evaluate the TAS5270M performance and capabilities, a fully populated evaluation board has been created. This board is shown in Figure 1-1. Connected to a PC, an external power supply (4.5 V ≤ PVDD ≤ 26.4 V) and a signal source, the TAS5270M Evaluation Board easily exercises the amplifier's features.

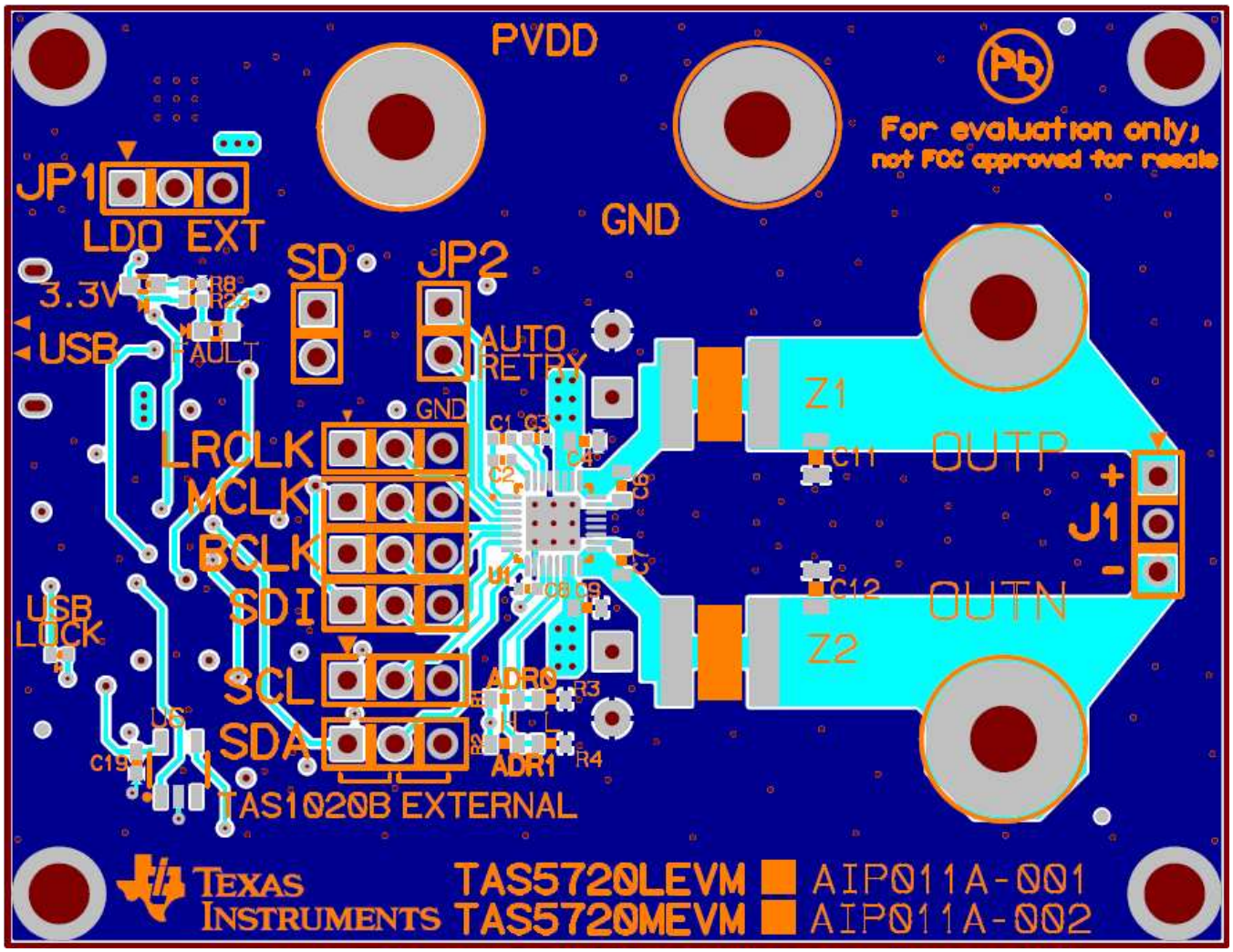

Figure 1-1. TAS5720M Evaluation Board

Quick Start Guide

1. Ensure all the jumpers are set correctly according to Table 2-1 and Figure 2-1.
2. Connect a speaker's positive output terminal and negative output terminal respectively to OUTP (RED) and OUTN (BLACK) on the EVM board. Be careful not to mix up OUTP and PVDD terminals, since the colors are the same. The same applies to OUTN and GND terminals.
3. Connect a power supply (4.5 V-26.4 V) and ground reference respectively to PVDD (RED) and GND (BLACK) on the EVM board.
4. Connect a micro USB cable to EVM and PC to generate 3.3 V supply.
5. Go to **Control Panel**, **Sound** and select **USB-AudioEVM** under the **Playback** tab. Click on **Set Default** to make it the default playback device. Click on **Properties** and under the **Advanced** tab, make sure that the **Default Format** is shown as 2 channel, 16 bit, 48000 Hz (DVD Quality) in Figure 2-2 below.
6. Power on the power supply after checking that all the connections are correctly.
7. Load a music file in the Windows Media Player. Play that audio file and listen to the output.

Table 2-1. TAS5720MEVM Default Jumper Settings

Jumper	Position	Comments
JP1	LEFT SIDE	Use LDO +3.3 V
JP2	IN	Enable Auto-Retry
SD	OUT	Keep device active
LRCLK	LEFT SIDE	Connect LRCLK to TAS5720M
MCLK	LEFT SIDE	Connect MCLK to TAS5720M
BCLK	LEFT SIDE	Connect BLK to TAS5720M
SDI	LEFT SIDE	Connect SDI to TAS5720M
SCL	LEFT SIDE	Connect SCL to TAS5720M
SDA	LEFT SIDE	Connect SDA to TAS5720M

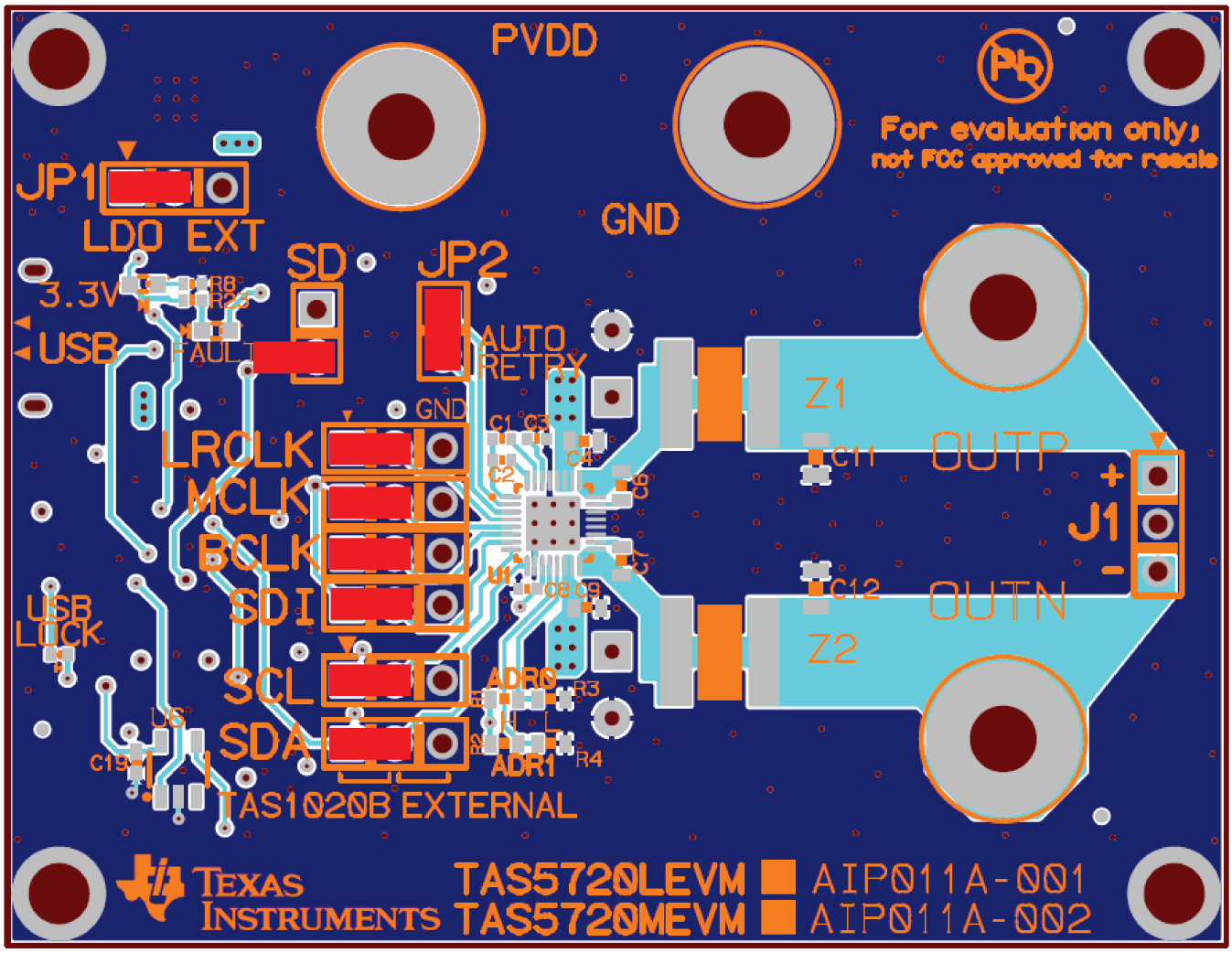

Figure 2-1. TAS5720MEVM Default Jumper Settings

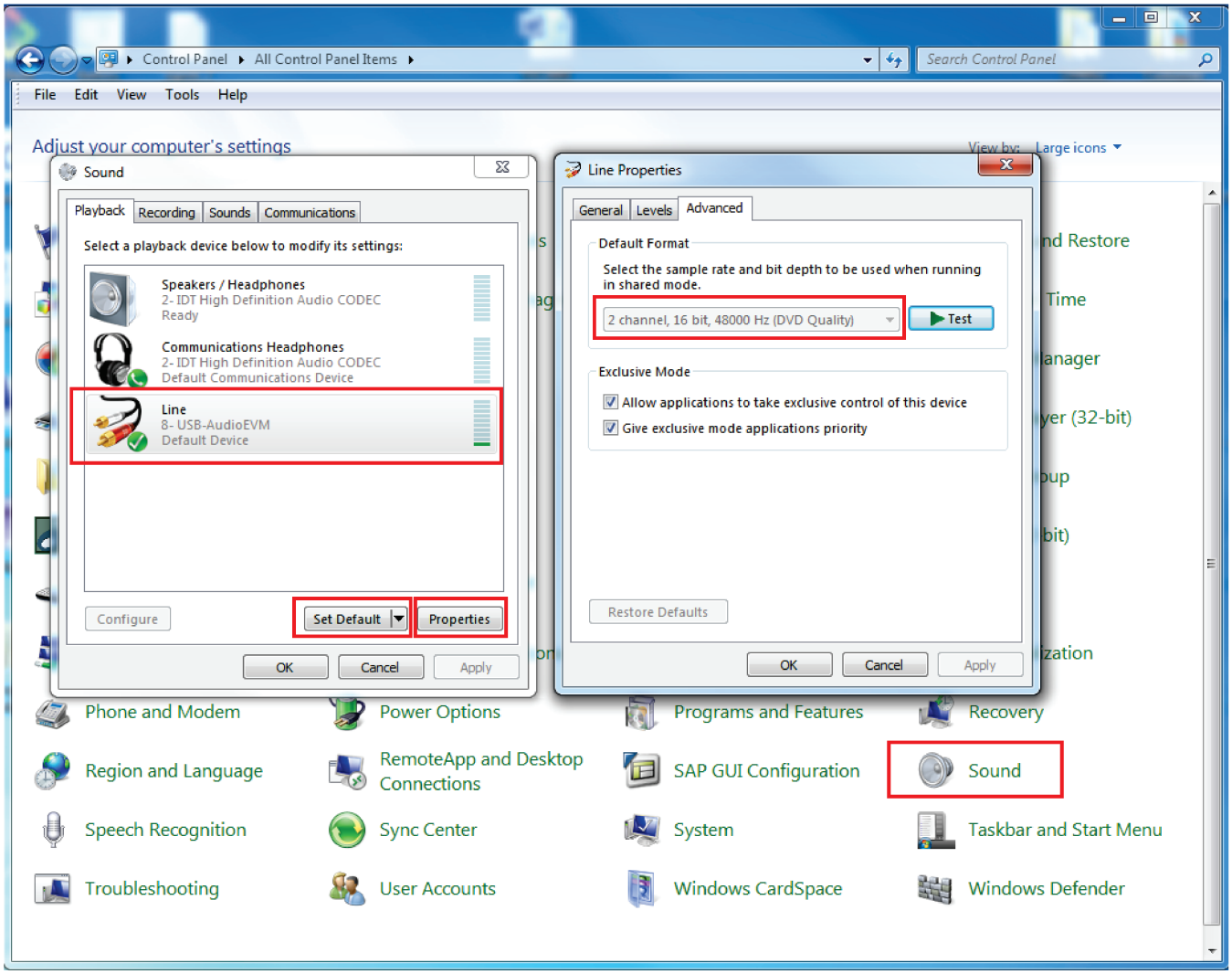

Figure 2-2. Default Format

General Description

The TAS5720M device is a high-efficiency mono Class-D audio power amplifier optimized for high transient power capability to use the dynamic power headroom of small loudspeakers. It is capable of delivering more than 15-W continuously into a 4-Ω speaker. The device has two address pins, which allow up to 8 I2C addressable devices to share a common TDM bus.

The TAS5720M device SAIF supports a variety of standard stereo serial audio formats including I2S, Left Justified and Right Justified. It also supports a time division multiplexed (TDM) format that is capable of transporting up to 8 channels of audio data on a single bus.

Operating Conditions

Table 4-1. Operating Conditions

PVDD and AVDD	4.5 V to 26.4 V
DVDD	3.0 V to 3.6 V
Minimum speaker load	3.2 Ω
I2C Clock Frequency	Up to 400 kHz

PCB Layout Guidelines

- Pay special attention to the power stage power supply layout. Each H-bridge has two PVDD input pins so that decoupling capacitors can be placed nearby. Use at least a 0.1-µF capacitor of X5R quality or better for each set of inputs.
- Keep the current circulating loops containing the supply decoupling capacitors, the H-bridges in the device and the connections to the speakers as tight as possible to reduce emissions.
- Use ground planes to provide the lowest impedance for power and signal current between the device and the decoupling capacitors. The area directly under the device should be treated as a central ground area for the device, and all device grounds must be connected directly to that area.
- Use a via pattern to connect the area directly under the device to the ground planes in copper layers below the surface. This connection helps to dissipate heat from the device.
- Avoid interrupting the ground plane with circular traces around the device. Interruption disconnects the copper and interrupt flow of heat and current. Radial copper traces are better to use if necessary.

This section includes the EVM schematic, board layout and BOM.

6.1 TAS5720MEVM Schematic

Figure 6-1 and Figure 6-2 illustrate the schematic for the TAS5720MEVM.

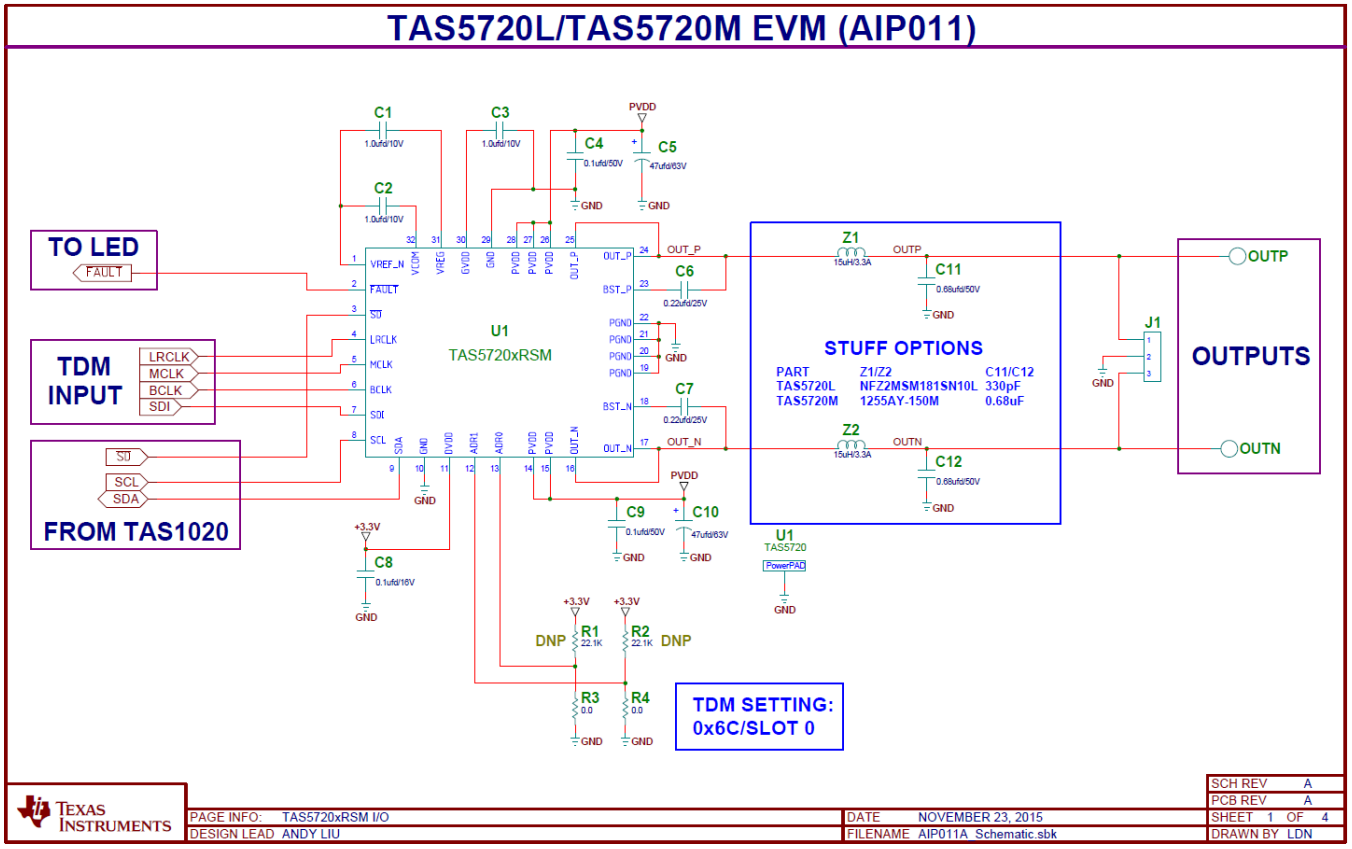

Figure 6-1. TAS5720MEVM Schematic (1 of 2)

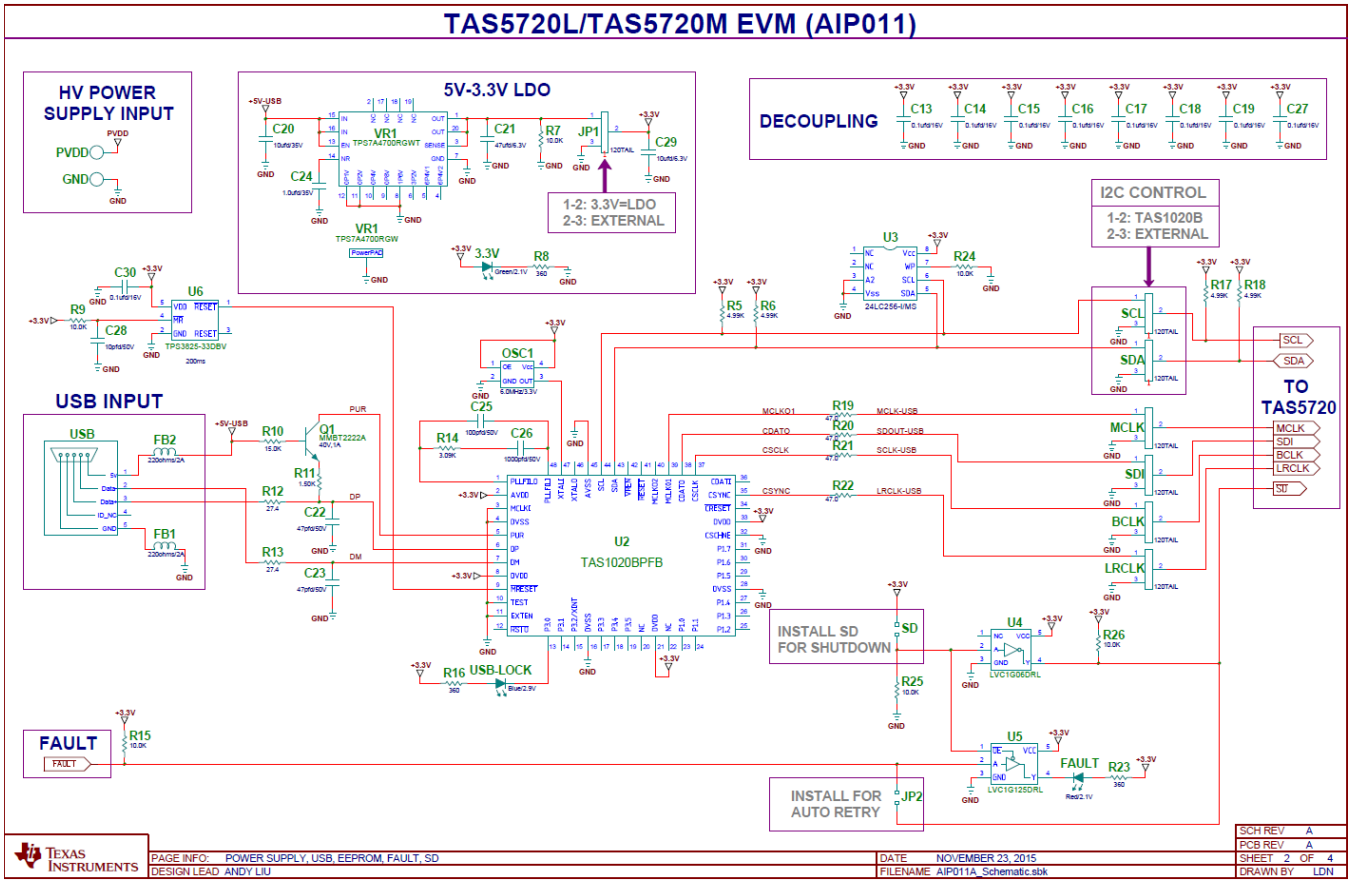

Figure 6-2. TAS5720MEVM Schematic (2 of 2)

6.2 TAS5720MEVM PCB Layout

Figure 3 through Figure 12 illustrate the PCB layouts for this EVM.

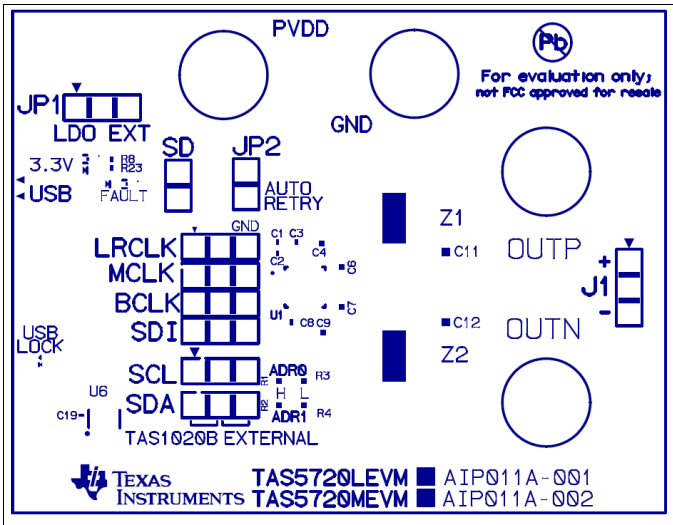

Figure 3. Top Silkscreen

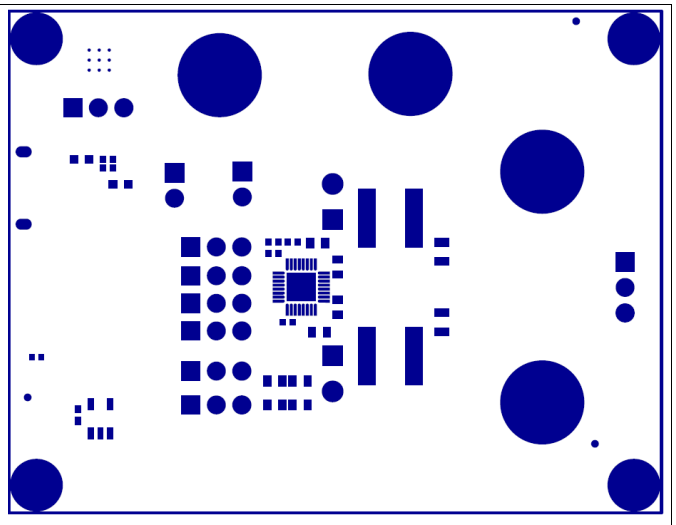

Figure 4. Top Solder Mask

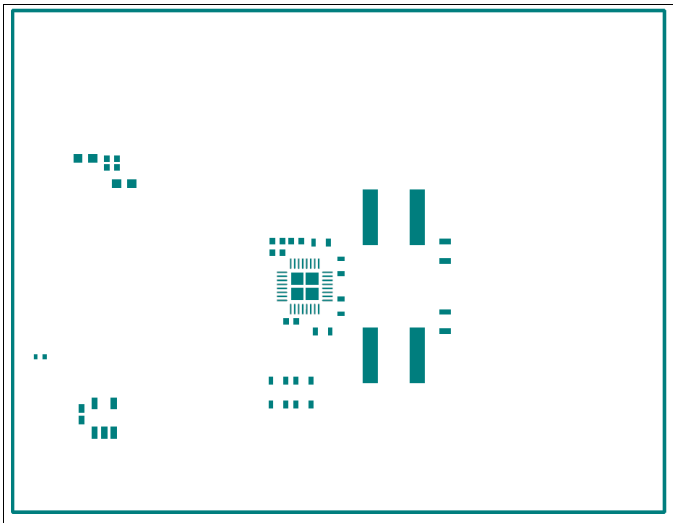

Figure 5. Top Solder Paste

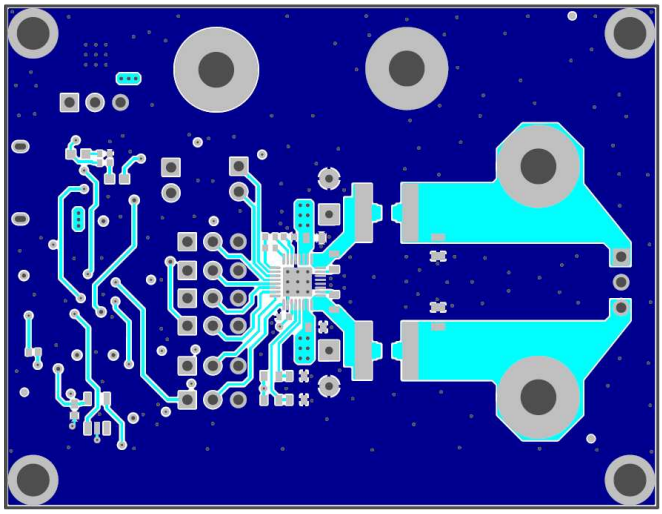

Figure 6. Top Layer

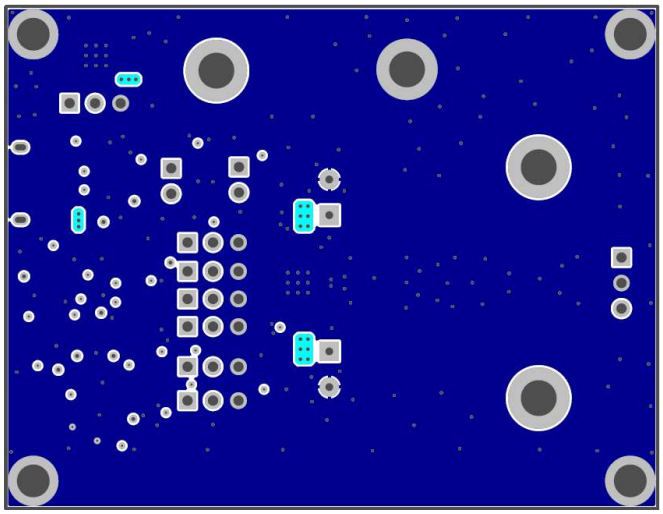

Figure 7. Layer 2

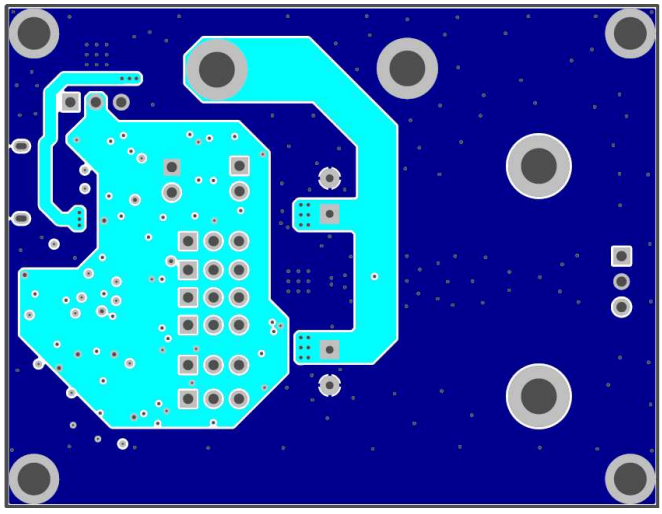

Figure 8. Layer 3

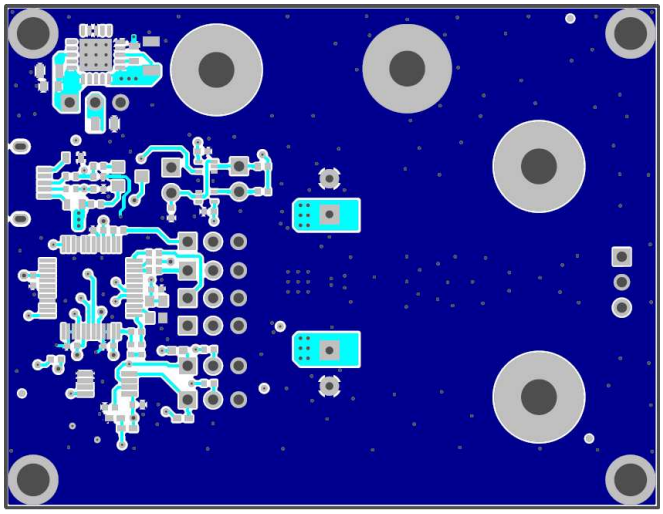

Figure 9. Bottom Layer

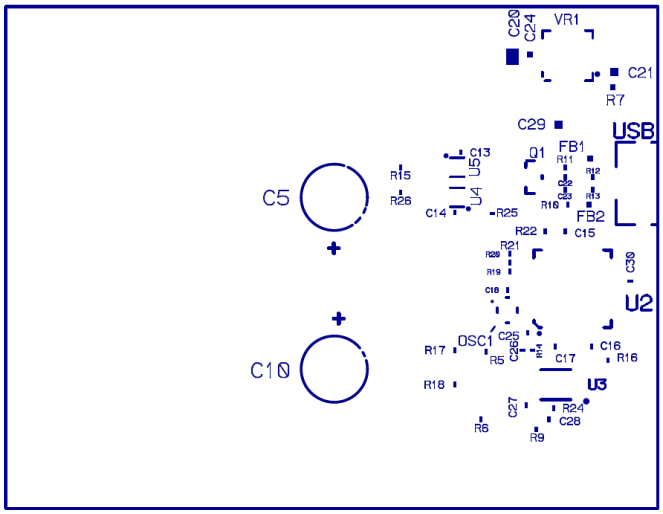

Figure 10. Bottom Silkscreen

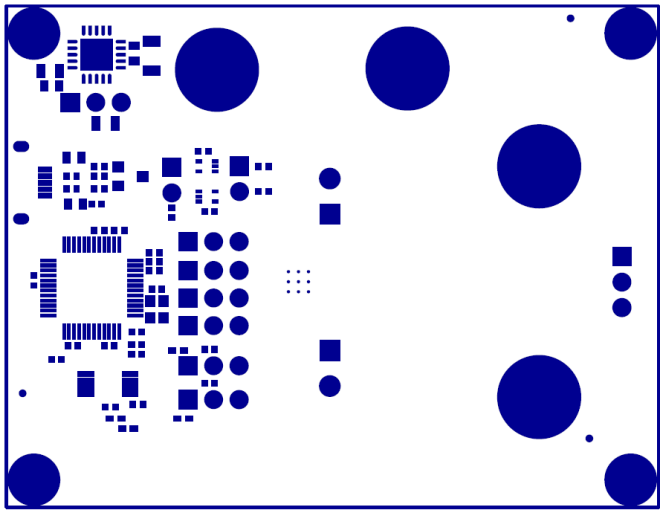

Figure 11. Bottom Solder Mask

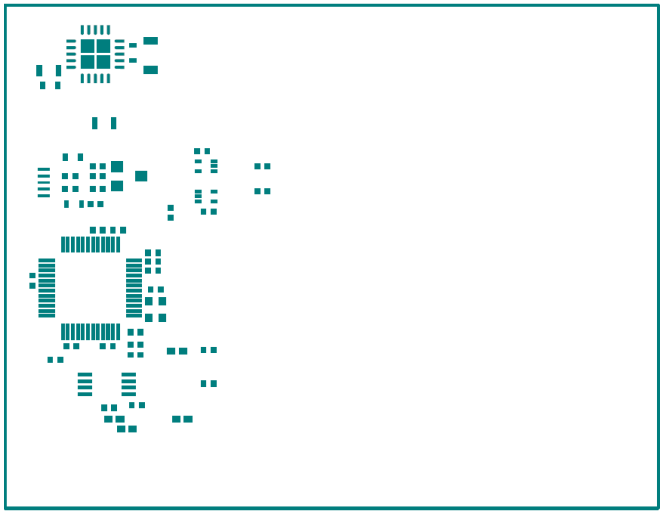

Figure 12. Bottom Solder Paste

6.3 TAS5720MEVM Bill of Materials

Table 6-1. Bill of Materials

ITEM	MANU PART NUM	MANU	QTY	REF DESIGNATORS	DESCRIPTION
1	TAS5720MRSM	TEXAS INSTRUMENTS	1	U1	DIGITAL INPUT MONO CLASS-D AUDIO AMPLIFIER QFN32-RSM ROHS
2	TAS1020BPFB	TEXAS INSTRUMENTS	1	U2	USB STREAMING CONTROLLER TQFP48-PFB ROHS
3	24LC256-I/MS	MICROCHIP	1	U3	SERIAL EEPROM I2 C 256 K 400 kHz MSOP8-MS ROHS
4	SN74LVC1G06DRLR	TEXAS INSTRUMENTS	1	U4	LOW POWER INVERTER OPEN DRAIN OUTS SOT553-DRL5 ROHS
5	SN74LVC1G125DRLR	TEXAS INSTRUMENTS	1	U5	SINGLE BUS BUFFER GATE WITH 3-STATE OUTPUT SOT553-DRL5 ROHS
6	TPS3825-33DBVR	TEXAS INSTRUMENTS	1	U6	PROCESSOR SUPERVISORY CIRCUITS 2.93 V 200 ms SOT23-DBV5 ROHS
7	TPS7A4700RGWT	TEXAS INSTRUMENTS	1	VR1	RF LDO VOLT REG, 36 V,1 A, 4.17 uVRMS QFN20-RGW ROHS
8	MMBT2222A-7-F	DIODES INC.	1	Q1	TRANSISTOR NPN GENERAL PURPOSE 40 V 1 A SOT23 DBV3 ROHS

Table 6-1. Bill of Materials (continued)

9	625L3I006M00000	CTS FREQUENCY CONTROLS	1	OSC1	OSCILLATOR SMT 6.0 MHz 3.3 V OUT-ENABLE ROHS
10	SMLP12BC7TT86	ROHM SEMICONDUCTOR	1	USB-LOCK	LED BLUE SMD0402 2.9 V 10 mA ROHS
11	LTST-C190EKT	LITE-ON INC.	1	FAULT	LED RED SMD0603 2.1 V 10 mA ROHS
12	LTST-C190GKT	LITE-ON INC.	1	3.3V	LED GREEN SMD0603 2.1 V 10 mA ROHS
13	C1005X5R1A105K	TDK CORP	3	C1, C2, C3	CAP SMD0402 CERM 1.0 UFD 10 V 10% X5R ROHS
14	C1608X7R1H104K	TDK	2	C4, C9	CAP SMD0603 CERM 0.1 UFD 50 V 10% X7R ROHS
15	EEU-FC1J470	PANASONIC	2	C5, C10	CAP THRU ALUM-ELECT FC SERIES 47 ufd 63 V 20% 8x3.5x11.5 mm ROHS
16	06033D224KAT2A	AVX	2	C6, C7	CAP SMD0603 CERM 0.22 UFD 25 V 10% X5R ROHS
17	GRM155R71C104KA88J	MURATA	10	C8, C13, C14, C15, C16, C17, C18, C19, C27, C30	CAP SMD0402 CERM 0.1 UFD 16 V X7R 10% ROHS
18	C2012X7R1H684M125AB	TDK	2	C11, C12	CAP SMD0805 CERM 0.68 UFD 50 V 20% X7R ROHS
19	GMK316AB7106KL-TR	TAIYO YUDEN	1	C20	CAP SMD1206 CERM 10 UFD 35 V 10% X7R ROHS
20	JMK212BJ476MG-T	TAIYO YUDEN	1	C21	CAP SMD0805 CERM 47 UFD 6.3 V 20% X5R ROHS
21	500R07N470JV4T	JOHANSON	2	C22, C23	CAP SMD0402 CERM 47 pfd 50 V 5% COG ROHS
22	GMK107BJ105KA-T	TAIYO YUDEN	1	C24	CAP SMD0603 CERM 1.0 UFD 35 V 10% X5R ROHS
23	CC0402JRNPO9BN101	YAGEO	1	C25	CAP SMD0402 CERM 100 pfd 50 V 5% NPO ROHS
24	GRM1555C1H102JA01D	MURATA	1	C26	CAP SMD0402 CERM 1000 pfd 5% 50 V COG ROHS
25	CGA2B2C0G1H100D050BD	DK CORP.	1	C28	CAP SMD0402 CERM 10 pfd 50 V +0.5 pfd COG ROHS
26	GRM21BR70J106KE76L	MURATA	1	C29	CAP SMD0805 CERM 10 UFD 6.3 V 10% X7R ROHS
27	MPZ1608S221A	TDK	2	FB1, FB2	FERRITE CHIP, 220 Ω 2 A 100 MHZ SMD 0603 ROHS

Table 6-1. Bill of Materials (continued)

28	ERJ-3GEY0R00V	PANASONIC	2	R3, R4	RESISTOR SMD0603 0.0 Ω 5% THICK FILM 1/10 W ROHS
29	ERJ-2RKF4991X	PANASONIC	4	R5, R6, R17, R18	RESISTOR SMD0402 4.99 K 1%,1/16 W ROHS
30	ERJ-3EKF1002V	PANASONIC	1	R7	RESISTOR SMD0603 10.0 K 1% THICK FILM 1/10 W ROHS
31	CRCW0402360RFKED	VISHAY	3	R8, R16, R23	RESISTOR SMD0402 360 1/16 W 1% ROHS
32	CRCW040210K0FKED	VISHAY	5	R9, R15, R24, R25, R26	RESISTOR SMD0402 10.0 K Ω 1% 1/16 W ROHS
33	RC0402FR-0715KL	YAGEO	1	R10	RESISTOR SMD0402 THICK FILM 15.0 K Ω 1% 1/16 W ROHS
34	RMCF0402FT1K50	STACKPOLE ELECTRONICS	1	R11	RESISTOR SMD0402 1.50K Ω 1% 1/16 W ROHS
35	ERJ-2RKF27R4X	PANASONIC	2	R12, R13	RESISTOR SMD0402 THICK FILM 27.4 Ω 1/10 W 1% ROHS
36	RC0402FR-073K09L	YAGEO	1	R14	RESISTOR SMD0402 THICK FILM 3.09 K Ω 1% 1/16 W ROHS
37	RC0402FR-0747RL	YAGEO	4	R19, R20, R21, R22	RESISTOR SMD0402 THICK FILM 47.0 Ω 1% 1/16 W ROHS
38	1255AY-150M	TOKO JAPAN	2	Z1, Z2	INDUCTOR SMT 15 µH 3.3 A 63 mΩ 20% DG6045C ROHS
39	PBC02SAAN	SULLINS	2	SD, JP2	HEADER THRU MALE 2 PIN 100 LS 120 TAIL GOLD ROHS
40	PBC03SAAN	SULLINS	8	J1, JP1, SCL, SDA, SDI, BCLK, MCLK, LRCLK	HEADER THRU MALE 3 PIN 100 LS 120 TAIL GOLD ROHS
41	ZX62WD1-B-5PC	HIROSE	1	USB	JACK USB FEMALE TYPEB MICRO SMT-RA 5PIN ROHS
42	7006	KEYSTONE ELECTRONICS	2	OUTP, PVDD	BINDING POST, RED, 15 A ECONO ROHS
43	7007	KEYSTONE ELECTRONICS	2	GND, OUTN	BINDING POST, BLACK, 15 A ECONO ROHS
44	969102-0000-DA	3M	11	J1, JP1, JP2, SCL, SD, SDA, SDI, BCLK, MCLK, LRCLK	SHUNT BLACK AU FLASH 0.100 LS OPEN TOP ROHS

Table 6-1. Bill of Materials (continued)

45	CRCW060322K1FKEA	VISHAY	0	R1, R2	RESISTOR SMD0603 22.1 K Ω 1% 1/10 W ROHS
46	2027	KEYSTONE ELECTRONICS	4	STANDOFFS	ROUND STANDOFF 4-40 ALUM 1/2" ROHS
47	PMSSS 440 0025 PH	B&F FASTENER	4	STANDOFF SCREWS	MACHINE SCREW PAN PHILLIPS 4-40 ROHS

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